

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6190xxxx7R-G
Typical Mass: 1.8 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.154	Silicon	85400	7440-21-3
		- Arsenic	<1	7440-38-2
Lead pad	0.386	Nickel	214400	7440-02-0
		Gold	1700	7440-57-5
Die attach	0.018	Epoxy Resin	9700	—
		Acrylic Resin	5800	—
Bonding wire	0.045	Gold	25200	7440-57-5
Resin	1.036	Silica	575400	60676-86-0
		Epoxy Resin	32900	—
		Phenol Resin	29600	—
		Metal hydroxide	19700	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."